

30mA, 600V N-CHANNEL DEPLETION-MODE FIELD-EFFECT TRANSISTOR

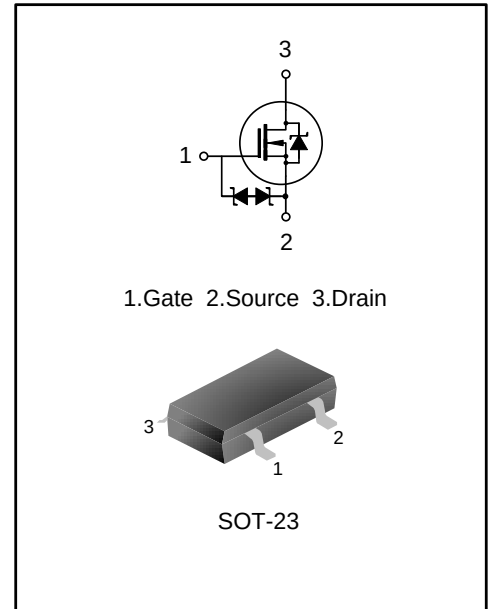
GENERAL DESCRIPTION

SVD501DEAG is an N-channel depletion-mode power MOS field effect transistor which is produced using Silan VDMOS technology. The improved process and cell structure have been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

It's widely used in electronic ballasts and low power SMPS.

FEATURES

- 30mA, 600V
- Depletion-mode (Normally-on)
- Improved ESD ability
- Fast switching
- Improved dv/dt capability



ORDERING INFORMATION

Part No.	Package	Marking	Hazardous substance control	Packing Type
SVD501DEAGTR	SOT-23	501DE	Halogen free	Tape & Reel

ABSOLUTE MAXIMUM RATINGS (T_C=25°C UNLESS OTHERWISE NOTED)

Characteristics		Symbol	Rating	Unit
Drain-Source Voltage		V _{DS}	600	V
Gate-Source Voltage		V _{GS}	±20	V
Drain Current	T _C =25°C	I _D	0.03	A
	T _C =70°C		0.024	
Drain Current Pulsed		I _{DM}	0.12	A
Power Dissipation(T _C =25°C) - Derate above 25°C		P _D	0.8	W
			0.007	W/°C
Operation Junction Temperature Range		T _J	-55~+150	°C
Storage Temperature Range		T _{stg}	-55~+150	°C

THERMAL CHARACTERISTICS

Characteristics	Symbol	Rating	Unit
Thermal Resistance, Junction-to-Case	R _{θJC}	150	°C/W
Thermal Resistance, Junction-to-Ambient	R _{θJA}	250	°C/W

ELECTRICAL CHARACTERISTICS (T_C=25°C UNLESS OTHERWISE NOTED)

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain -Source Breakdown Voltage	BV _{DSS}	V _{GS} =-5V, I _D =250μA	600	--	--	V
Drain-Source Leakage Current	I _{D(off)}	V _{DS} =600V, V _{GS} =-5V	--	--	0.1	μA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	--	--	±10	μA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =3V, I _D =8μA	-2.7	--	-1.0	V
On-state drain current	I _{DSS}	V _{GS} =0V, V _{DS} =25V	12	--	--	mA
Static Drain- Source On State Resistance	R _{DS(on)}	V _{GS} =0V, I _D =3mA	--	310	500	Ω
		V _{GS} =10V, I _D =16mA	--	330	500	
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =-5V, f=1.0MHz	--	10	--	pF
Output Capacitance	C _{oss}		--	2.9	--	
Reverse Transfer Capacitance	C _{rss}		--	0.12	--	
Turn-on Delay Time	t _{d(on)}	V _{DD} =300V, I _D =0.01A V _{GS} =-5~7V R _G =6Ω (Note 1,2)	--	12	--	ns
Turn-on Rise Time	t _r		--	60	--	
Turn-off Delay Time	t _{d(off)}		--	25	--	
Turn-off Fall Time	t _f		--	100	--	
Total Gate Charge	Q _g	V _{DS} =400V, I _D =0.01A V _{GS} =-5V~7V (Note 1,2)	--	2.8	--	nC
Gate-Source Charge	Q _{gs}		--	0.55	--	
Gate-Drain Charge	Q _{gd}		--	1.6	--	

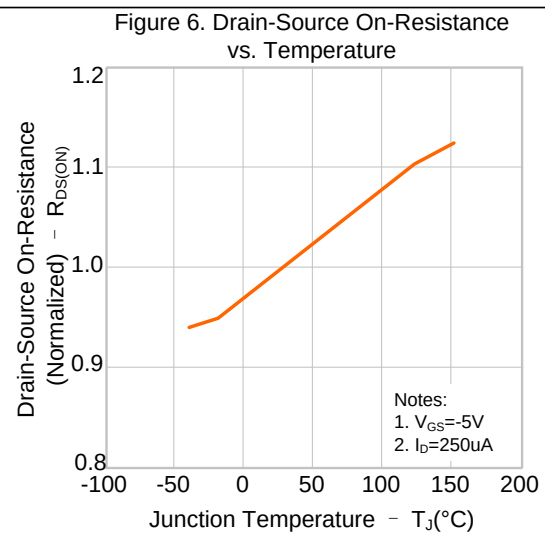
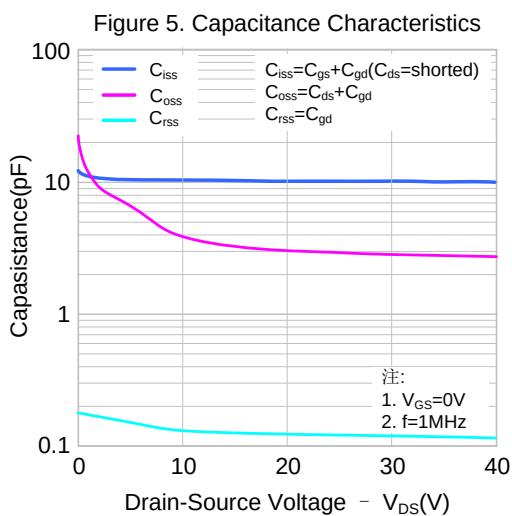
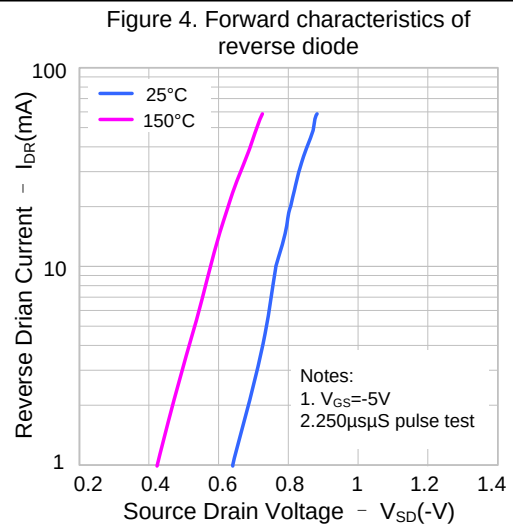
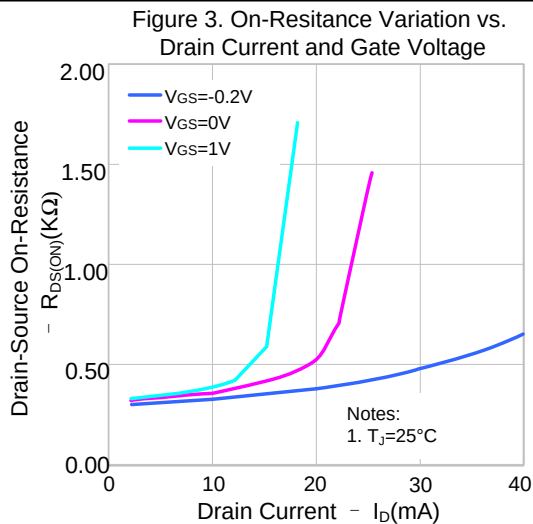
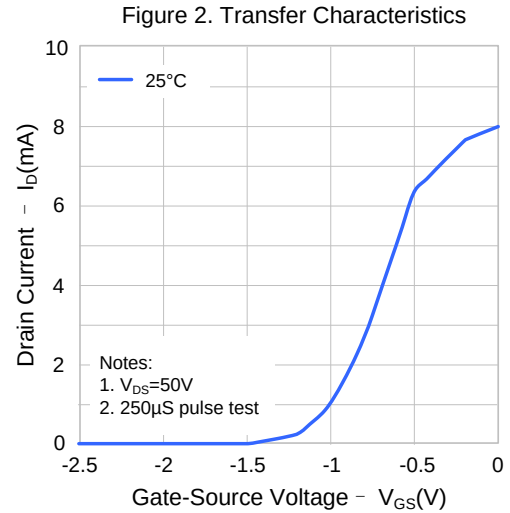
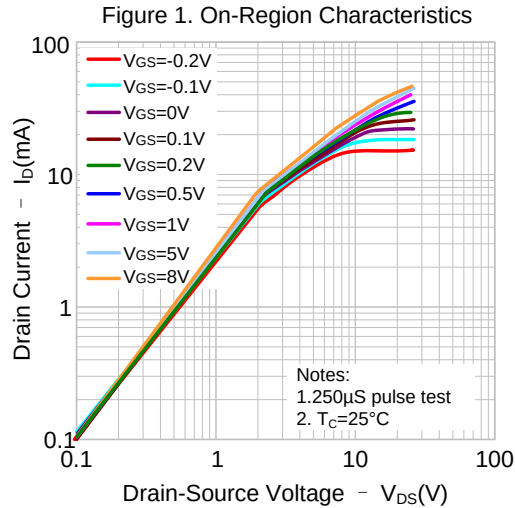
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_S	Integral Reverse P-N Junction Diode in the MOSFET	--	--	0.03	A
Pulsed Source Current	I_{SM}		--	--	0.12	
Diode Forward Voltage	V_{SD}	$I_F=16mA$, $V_{GS}=-5V$	--	--	1.2	V
Reverse Recovery Time	T_{rr}	$I_F=0.01A$, $V_R=300V$, $dI_F/dt=100A/\mu s$ (Note 2)	--	--	367	ns
Reverse Recovery Charge	Q_{rr}		--	--	963	nC

Notes:

1. Pulse Test: Pulse width $\leq$ pulse Test: cycle Tes
2. Essentially independent of operating temperature.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS (CONTINUED)

Figure 7. Breakdown Voltage vs. Temperature

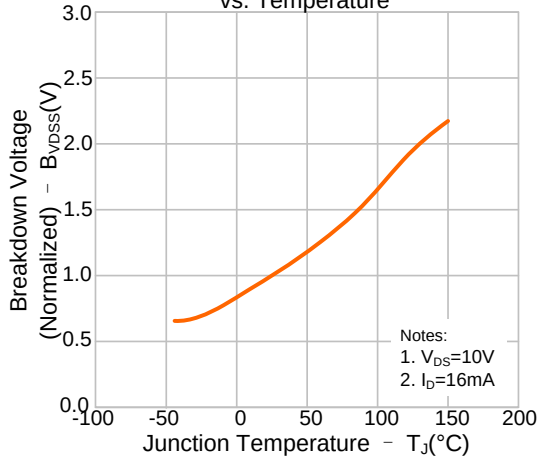


Figure 8. Gate Threshold Voltage vs. Temperature

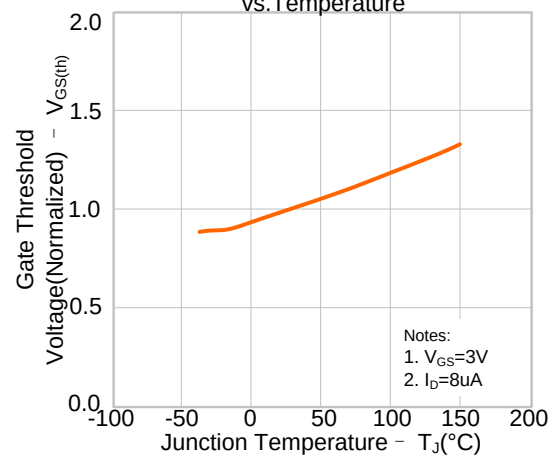


Figure 9. Power Dissipation vs. Case Temperature

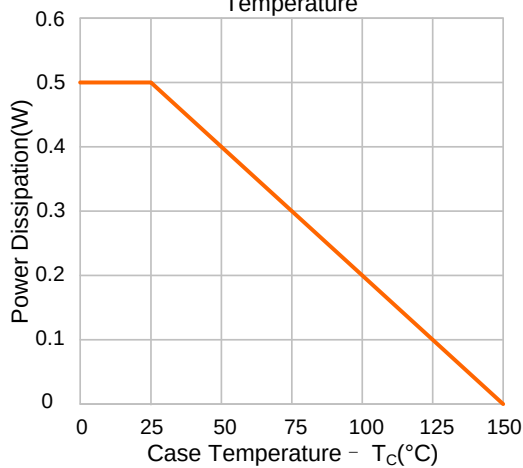


Figure 10. Max. Safe Operating Area

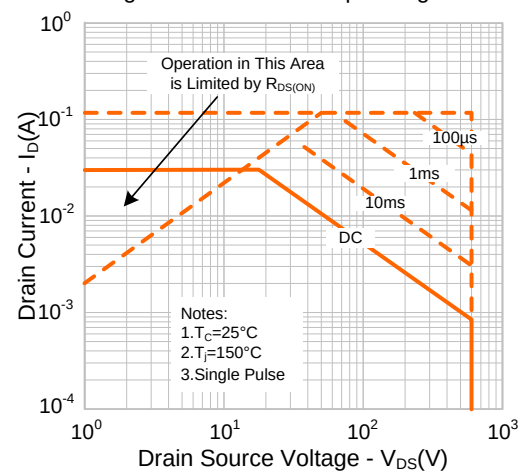


Figure 11. Maximum Drain Current vs. Case Temperature

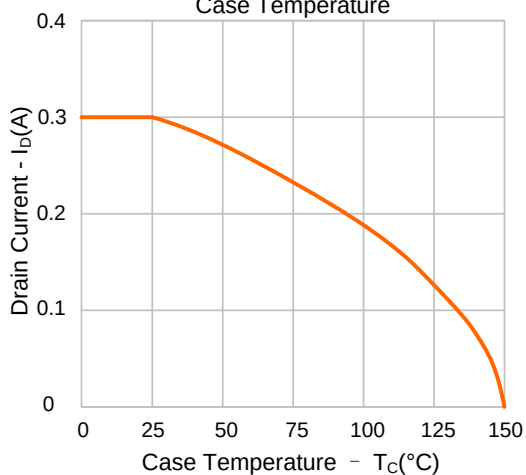
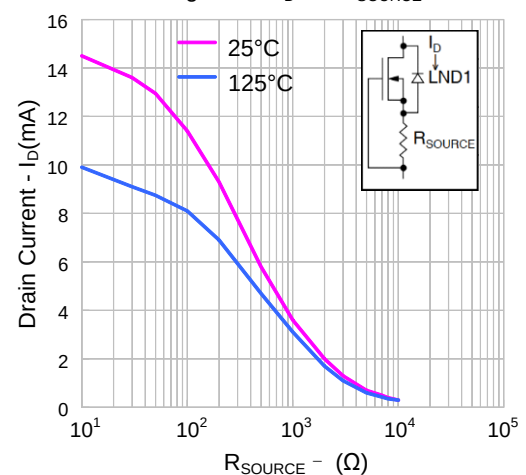


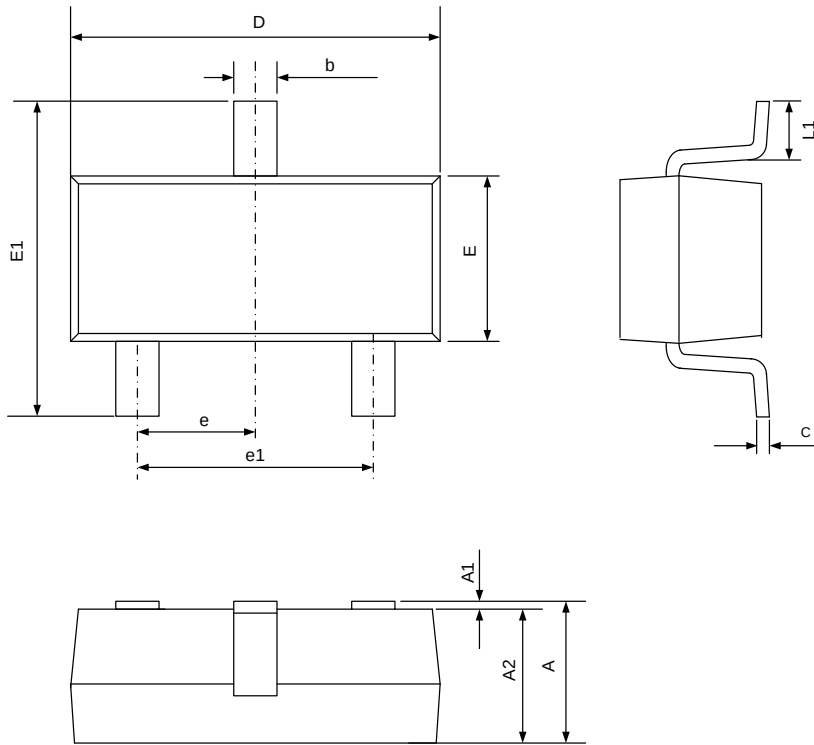
Figure 12. I_D vs. R_{SOURCE}



PACKAGE OUTLINE

SOT-23

UNIT: mm



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	1.3MAX		
A1	0	—	0.10
A2	0.80	1.00	1.20
b	0.35	0.40	0.55
c	0.08	—	0.20
D	2.70	2.90	3.10
E	1.10	1.30	1.50
E1	2.10	2.40	2.70
e	0.95BSC		
e1	1.70	1.90	2.10
L1	0.20	0.40	0.60

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- The instructions are subject to change without notice! Customers should obtain the latest relevant information before placing orders and should verify that such information is complete and current.
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- Product promotion is endless, our company will wholeheartedly provide customers with better products!
- Website: <http://www.silan.com.cn>

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Rev.: 1.7

Revision History:

1. Modify individual parameters
 2. Add the figure 12
-

Rev.: 1.6

Revision History:

1. Modify individual parameters
 2. Modify TYPICAL CHARACTERISTICS
-

Rev.: 1.5

Revision History:

1. Modify Tc of Drain Current
 2. Modify BV_{DSS}
-

Rev.: 1.4

Revision History:

1. Modify the curve
-

Rev.: 1.3

Revision History:

1. Modify Typical Characteristics
-

Rev.: 1.2

Revision History:

1. Modify "ELECTRICAL CHARACTERISTICS"
-

Rev.: 1.1

Revision History:

1. Update figure 3 and figure 7
-

Rev.: 1.0

Revision History:

1. Initial release
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